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Kind regards,

Team Nexperia

DATA SHEET

**PMEGX10BEA;
PMEGX10BEV**

1 A very low V_F MEGA Schottky
barrier rectifier

Product data sheet
Supersedes data of 2004 Apr 02

2004 Jun 14

1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA; PMEGXX10BEV

FEATURES

- Forward current: 1 A
- Reverse voltages: 20 V, 30 V, 40 V
- Very low forward voltage
- Ultra small and very small plastic SMD package
- Power dissipation comparable to SOT23.

APPLICATIONS

- High efficiency DC-to-DC conversion
- Voltage clamping
- Protection circuits
- Low voltage rectification
- Blocking diodes
- Low power consumption applications.

DESCRIPTION

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a very small SOD323 (SC-76) and ultra small SOT666 SMD plastic package.

MARKING

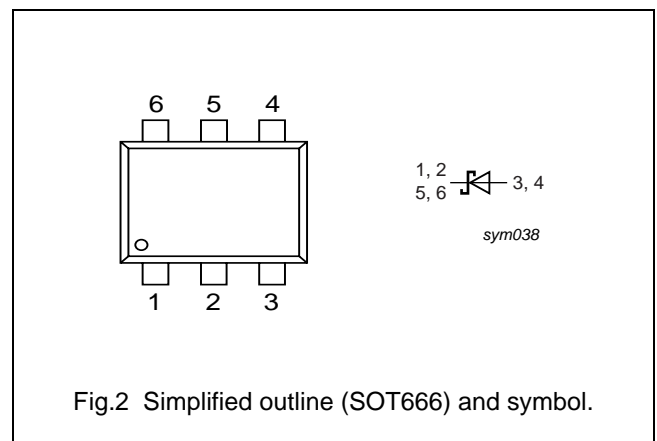
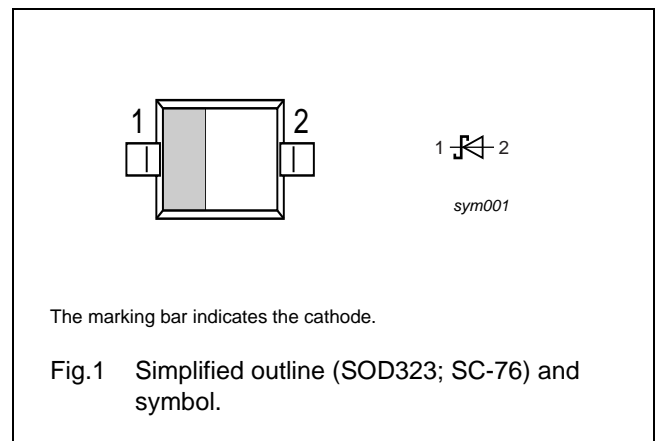
TYPE NUMBER	MARKING CODE
PMEG2010BEA	V1
PMEG3010BEA	V2
PMEG4010BEA	V3
PMEG2010BEV	G6
PMEG3010BEV	G5
PMEG4010BEV	G4

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
I_F	forward current	1	A
V_R	reverse voltage	20; 30; 40	V

PINNING

PIN	DESCRIPTION
PMEGXX10BEA (see Fig.1)	
1	cathode
2	anode
PMEGXX10BEV (see Fig.2)	
1, 2, 5, 6	cathode
3, 4	anode



1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PMEGXX10BEA	–	plastic surface mounted package; 2 leads	SOD323
PMEGXX10BEV		plastic surface mounted package; 6 leads	SOT666

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage PMEG2010BEA/PMEG2010BEV PMEG3010BEA/PMEG3010BEV PMEG4010BEA/PMEG4010BEV		–	20 30 40	V V V
I_F	continuous forward current	$T_s \leq 55^\circ\text{C}$; note 1	–	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.5$; note 2	–	3.5	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; square wave; note 2	–	10	A
T_j	junction temperature	note 3	–	150	$^\circ\text{C}$
T_{amb}	operating ambient temperature	note 3	–65	+150	$^\circ\text{C}$
T_{stg}	storage temperature		–65	+150	$^\circ\text{C}$

Notes

1. Refer to SOD323 (SC-76) and SOT666 standard mounting conditions.
2. Only valid if pins 3 and 4 are connected in parallel (SOT666 package).
3. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.

1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
PMEGXX10BEA (SOD323)				
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; notes 1 and 2	450	K/W
		in free air; notes 2 and 3	210	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point	note 4	90	K/W
PMEGXX10BEV (SOT666)				
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; notes 2 and 5	405	K/W
		in free air; notes 2 and 6	215	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point	note 4	80	K/W

Notes

1. Refer to SOD323 (SC-76) standard mounting conditions.
2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.
3. Device mounted on an FR4 printed-circuit board with copper clad 10 × 10 mm.
4. Solder point of cathode tab.
5. Refer to SOT666 standard mounting conditions.
6. Only valid if pins 3 and 4 are connected in parallel (SOT666 package).

CHARACTERISTICS

$T_{amb} = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	PMEG2010BEA/ PMEG2010BEV		PMEG3010BEA/ PMEG3010BEV		PMEG4010BEA/ PMEG4010BEV		UNIT
			TYP.	MAX.	TYP.	MAX.	TYP.	MAX.	
V_F	forward voltage	$I_F = 0.1\text{ mA}$	90	130	90	130	95	130	mV
		$I_F = 1\text{ mA}$	150	190	150	200	155	210	mV
		$I_F = 10\text{ mA}$	210	240	215	250	220	270	mV
		$I_F = 100\text{ mA}$	280	330	285	340	295	350	mV
		$I_F = 500\text{ mA}$	355	390	380	430	420	470	mV
		$I_F = 1000\text{ mA}$	420	500	450	560	540	640	mV
I_R	continuous reverse current	$V_R = 10\text{ V}$; note 1	15	40	12	30	7	20	μA
		$V_R = 20\text{ V}$; note 1	40	200	–	–	–	–	μA
		$V_R = 30\text{ V}$; note 1	–	–	40	150	–	–	μA
		$V_R = 40\text{ V}$; note 1	–	–	–	–	30	100	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$	66	80	55	70	43	50	pF

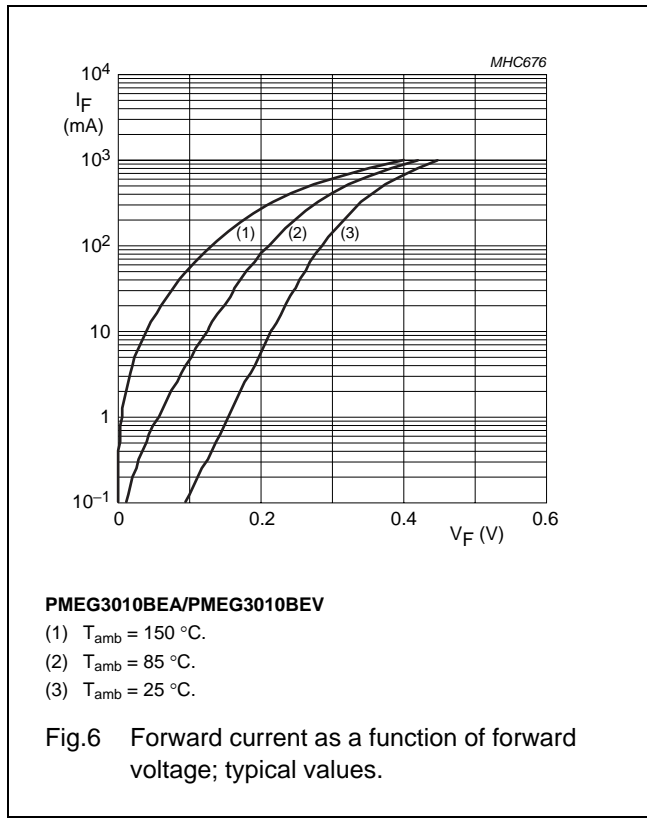
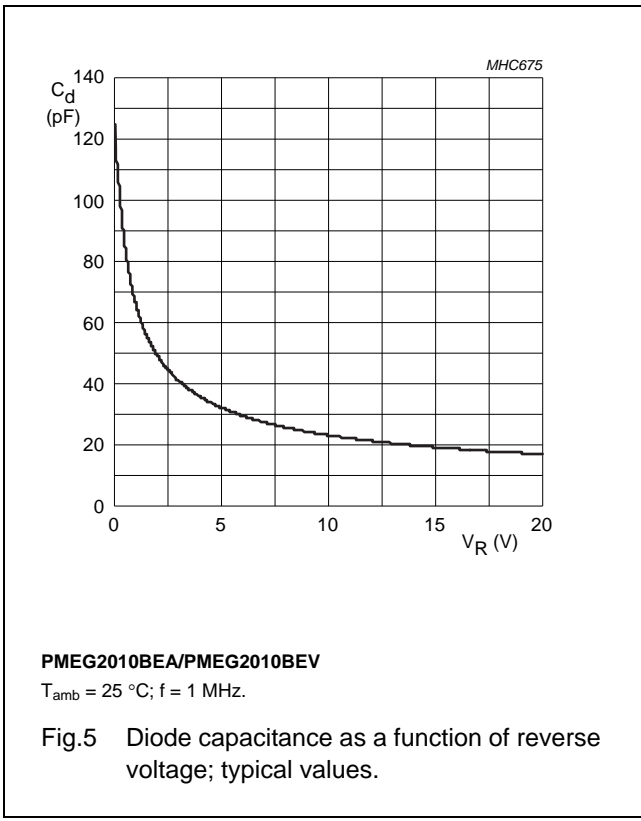
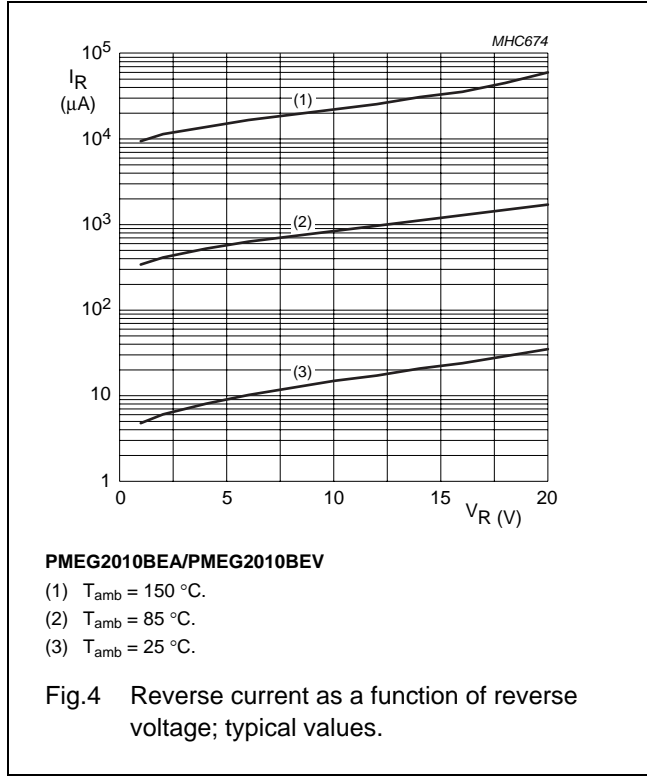
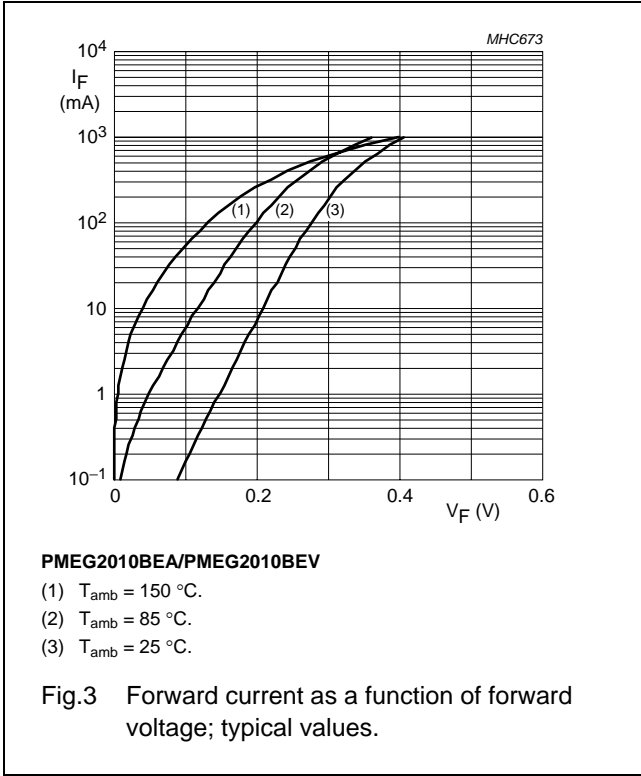
Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

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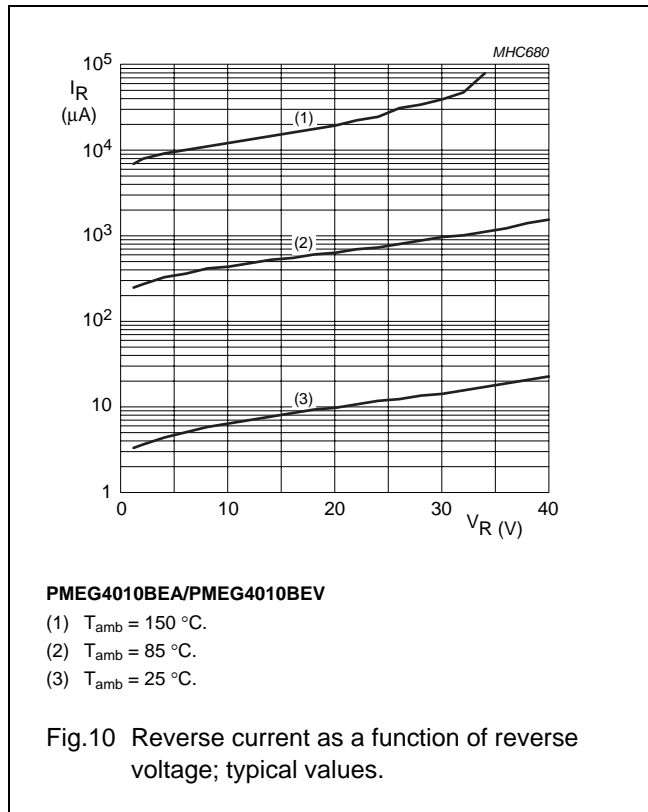
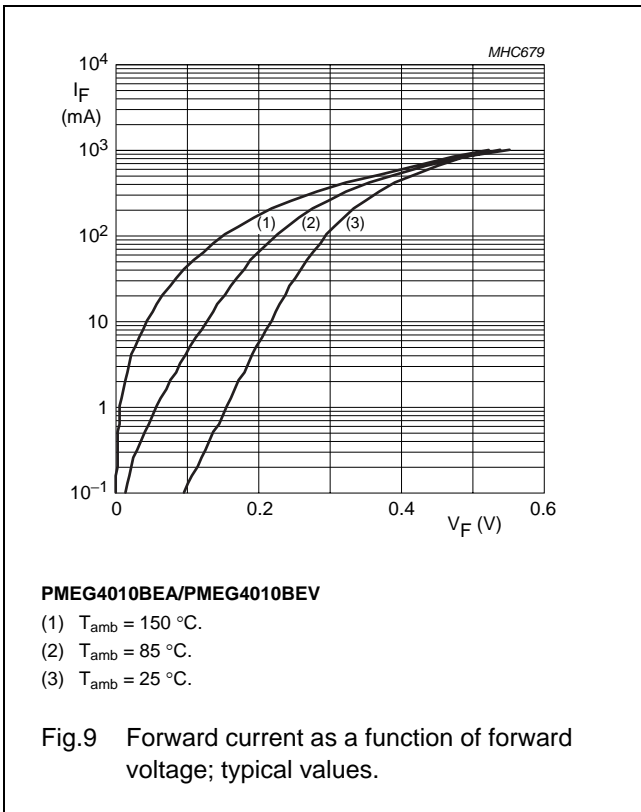
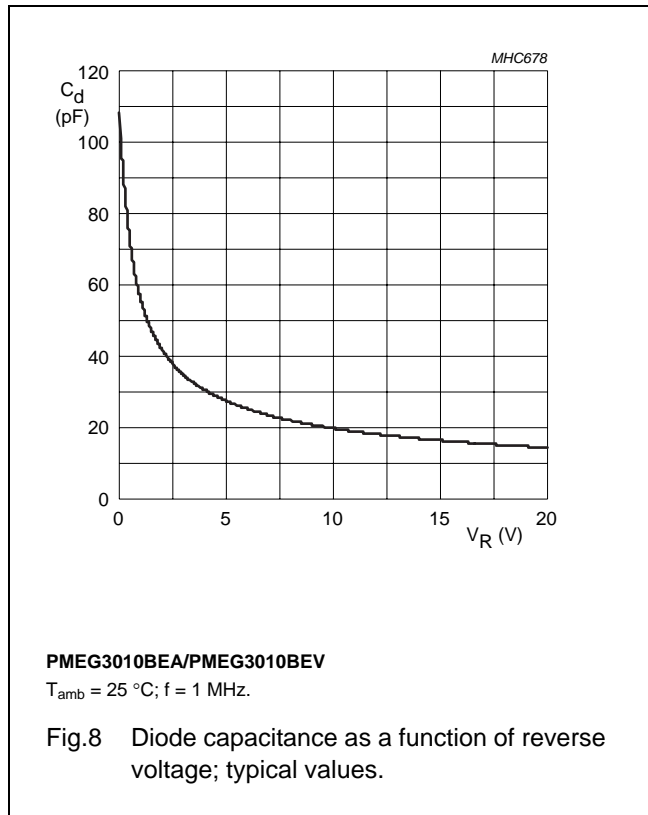
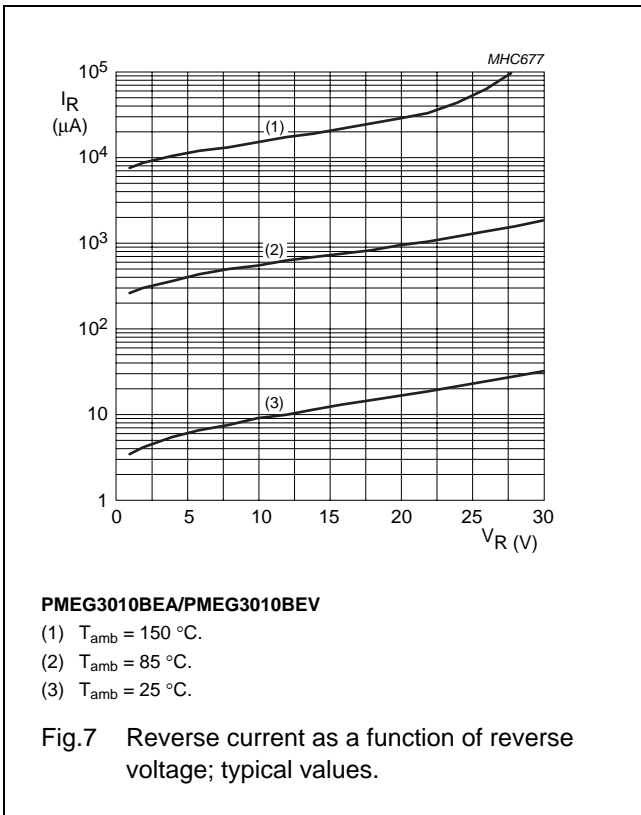
PMEGXX10BEA;
PMEGXX10BEV

GRAPHICAL DATA



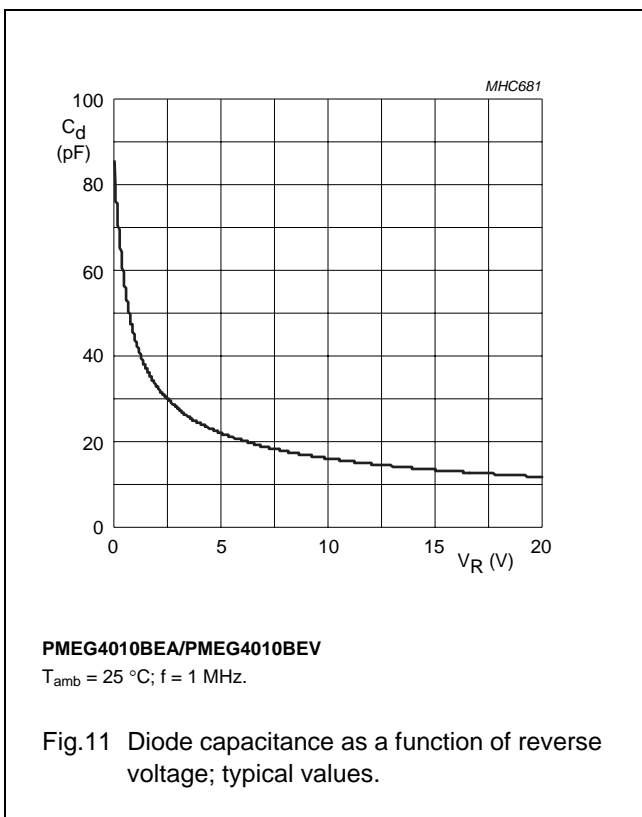
1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV



1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV



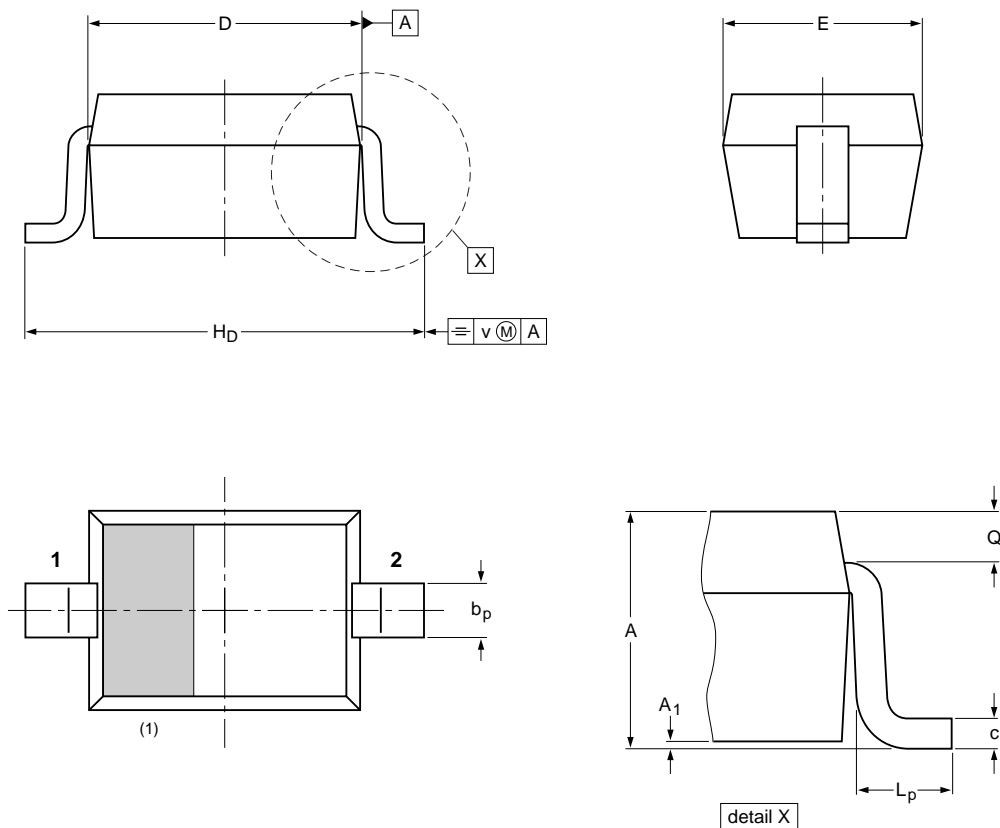
1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV

PACKAGE OUTLINES

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	H _D	L _p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

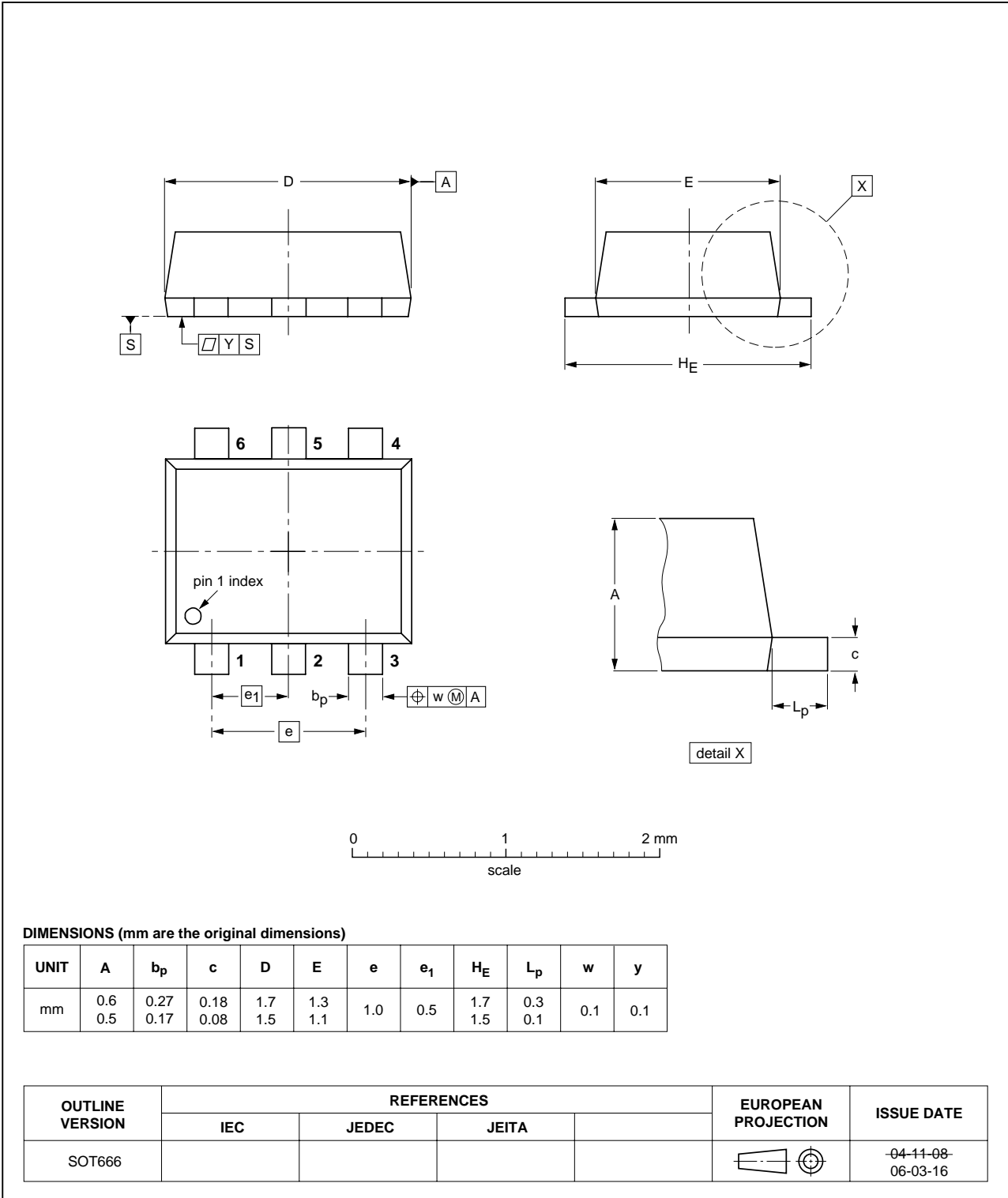
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		03-12-17 06-03-16

1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV

Plastic surface-mounted package; 6 leads

SOT666



1 A very low V_F MEGA Schottky barrier rectifier

PMEGXX10BEA;
PMEGXX10BEV

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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NXP Semiconductors

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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